



## Material Composition Sheet

Product: GS1582-IBE3  
 Package Type: BGA-100 Pin  
 Manufacturer: Gennum Corporation

Date: 06-Jun-2007

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Die		11.30	Al	0.07	0.60	6018
			Si	11.23	99.39	993982
			Sub-total:	11.30	99.99	1000000
Die Attach	Ablebond 2100A	5.11	Ag	3.94	77.00	770059
			Di-ester Resin	0.51	10.00	100000
			Epoxy Resin	0.33	6.49	64971
			Functionalized ester resin	0.33	6.49	64971
			Sub-total:	5.11	99.98	1000001
Mold Compound	KE-G1250	159.24	Carbon Black	0.80	0.49	4999
			Epoxy Resin	9.55	5.99	59997
			Phenol Resin	8.76	5.49	54999
			SiO2	140.13	88.00	880005
			Sub-total:	159.24	99.97	1000000
Solder Balls	SAC 405	48.64	Ag	1.95	4.00	40008
			Cu	0.24	0.49	4996
			Sn	46.45	95.49	954996
			Sub-total:	48.64	99.98	1000000
Substrate	BT	159.84	Acrylic resin	15.98	10.00	100000
			Au	0.88	0.54	5499
			Bisphenol	23.98	15.00	150000
			Cu	58.82	36.79	367999
			Epoxy Resin	12.79	7.99	79999
			Ni	2.40	1.50	15003
			SiO2	17.02	10.65	106500
			Triazol	27.97	17.50	175000
			Sub-total:	159.84	99.97	1000000
Wires	25_NL03F	3.69	Au	3.69	100.00	1000000
			Sub-total:	3.69	100.00	1000000
<b>Total:</b>		<b>387.82</b>				

### GENNUM CORPORATION

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